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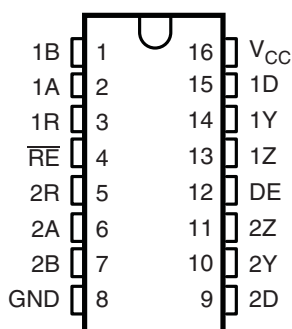
DUAL DIFFERENTIAL DRIVERS AND RECEIVERS

Check for Samples: [SN7534050](#), [SN7534051](#)

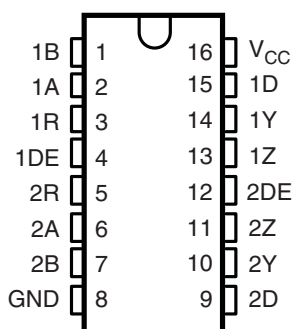
FEATURES

- Meet or Exceed Standards TIA/EIA-422-B and ITU Recommendation V.11
- Operate From Single 5-V Power Supply
- Driver Positive and Negative Current Limiting
- Receiver Input Sensitivity: $\pm 200\text{mV}$
- Receiver Input Impedance: 12 k Ω Min
- Driver 3-State Outputs
- Receiver 3-State Outputs (SN7534050 Only)

SN7534050...N OR NS PACKAGE
(TOP VIEW)



SN7534051...N OR NS PACKAGE
(TOP VIEW)



DESCRIPTION

The SN7534050 and SN7534051 dual differential drivers and receivers are monolithic integrated circuits designed to meet the requirements of ANSI standards TIA/EIA-422-B and ITU Recommendations V.11.

The driver outputs provide limiting for both positive and negative currents and thermal shutdown protection from line fault conditions on transmission bus line.

The SN7534050 combines dual 3-state differential drivers and dual 3-state differential input receivers. The drivers and receivers have active-high and active-low enables, respectively which can be externally connected together to function as direction control. SN7534051 drivers each have an individual active-high enable.

ORDERING INFORMATION

T _A	PACKAGE ^{(1) (2)}		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–20°C to 85°C	PDIP – N	Tube of 25	SN7534050N	SN7534050N
		Tube of 50	SN7534050NS	SN7534050
	SOP – NS	Reel of 2000	SN7534050NSR	SN7534050
		Tube of 25	SN7534051N	SN7534051N
		Tube of 50	SN7534051NS	SN7534051
		Reel of 2000	SN7534051NSR	SN7534051

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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FUNCTION TABLES

**Table 1. SN7534050,
SN7534051
Each Driver⁽¹⁾**

INPUT D	ENABLE DE	OUTPUTS	
		Y	Z
H	H	H	L
L	H	L	H
X	L	Z	Z

(1) H = high level, L = low level,
X = irrelevant, Z = high impedance
(off)

**Table 2. SN7534050
Each Receiver⁽¹⁾**

DIFFERENTIAL INPUTS, A–B	ENABLE RE	OUTPUT R
$V_{ID} \geq 0.2 \text{ V}$	L	H
$-0.2 \text{ V} < V_{ID} < 0.2 \text{ V}$	L	?
$V_{ID} \leq -0.2 \text{ V}$	L	L
X	H	Z

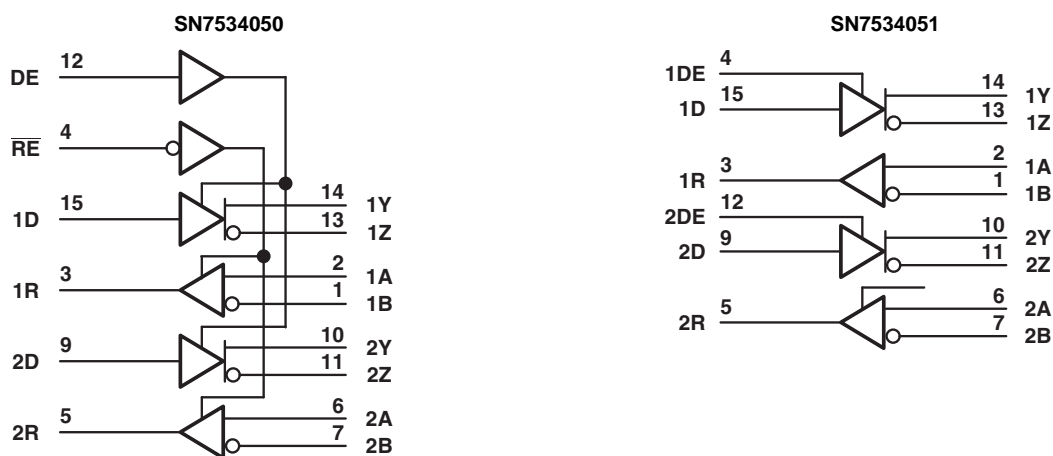
(1) H = high level, L = low level, ? = indeterminate, X = irrelevant,
Z = high impedance (off)

**Table 3. SN7534051
Each Receiver⁽¹⁾**

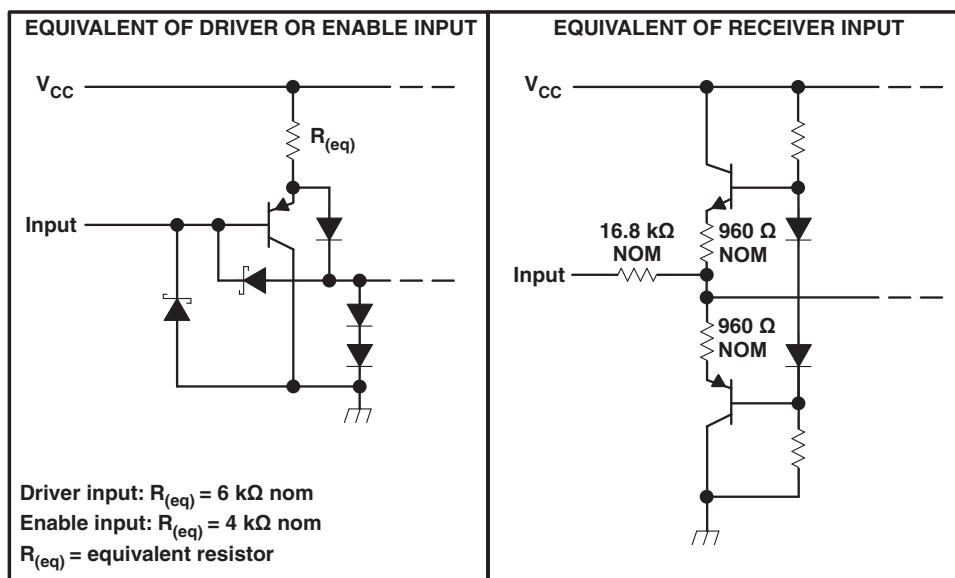
DIFFERENTIAL INPUTS, A–B	OUTPUT R
$V_{ID} \geq 0.2 \text{ V}$	H
$-0.2 \text{ V} < V_{ID} < 0.2 \text{ V}$?
$V_{ID} \leq -0.2 \text{ V}$	L

(1) H = high level, L = low level,
? = indeterminate

LOGIC DIAGRAMS



SCHEMATIC OF INPUTS



All resistor values are nominal.

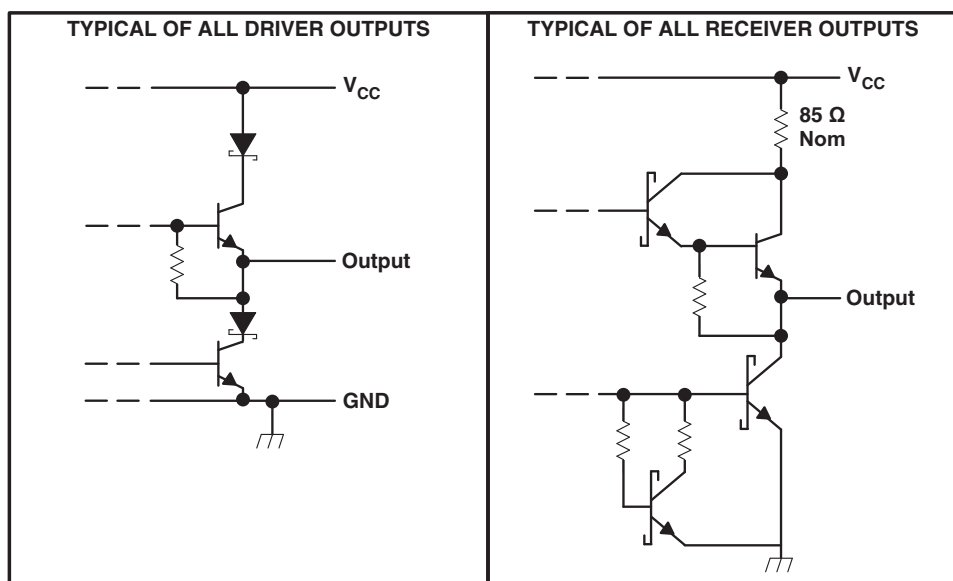
SN7534050, SN7534051



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SCHEMATIC OF OUTPUTS



All resistor values are nominal.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage ⁽²⁾			7	V
V _I	Input voltage	DE, \overline{RE} , D inputs		7	V
V _i	Receiver input voltage	A or B inputs		±25	V
V _{ID}	Receiver differential output voltage ⁽³⁾			±25	V
V _O	Driver output voltage range		–10	15	V
I _{OL}	Receiver low-level output current			50	mA
θ _{JA}	Package thermal impedance ⁽⁴⁾	N package		66	°C/W
		NS package		68	°C/W
	Operating free-air temperature range		–20	85	°C
T _{stg}	Storage temperature range		–65	150	°C
	Lead temperature, 1.6 mm (1/16 in) from case for 10 s			260	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages, except differential input voltage, are with respect to the network GND.
- (3) Differential input voltage is measured at the noninverting terminal, with respect to the inverting terminal.
- (4) The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.75	5	5.25	V
V _{IH}	High-level input voltage	DE, $\overline{\text{RE}}$, D	2			V
V _{IL}	Low-level input voltage		0.8			V
V _{IC}	Common-mode input voltage ⁽¹⁾	Receiver	±7			V
V _{ID}	Differential input voltage	Receiver	±12			V
I _{OH}	High-level output current	Driver	40			mA
		Receiver	−400			μA
I _{OL}	Low-level output current	Driver	−40			mA
		Receiver	16			
T _A	Operating free-air temperature		−20		85	°C

(1) Refer to TIA/EIA-422-B for exact conditions.

DRIVER SECTION

Electrical Characteristics

over recommended supply voltage and operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	High-level output voltage	V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = –20 mA		3.7		V
V _{OL}	Low-level output voltage	V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 20 mA		1.1		V
V _{OD1}	Differential output voltage	I _O = 0 mA	1.5		6	V
V _{OD2}	Differential output voltage ⁽²⁾	R _L = 100 Ω, See Figure 1	2			V
ΔV _{OD}	Change in magnitude of differential output voltage ⁽²⁾	R _L = 100 Ω, See Figure 1			±0.4	V
V _{OC}	Common-mode output voltage ⁽²⁾	R _L = 100 Ω, See Figure 1			±3	V
ΔV _{OC}	Change in magnitude of differential common-mode voltage ⁽²⁾	R _L = 100 Ω, See Figure 1			±0.4	V
I _{off}	Output current with power off ⁽²⁾	V _{CC} = 0 V	V _O = 6 V		100	µA
			V _O = –0.25 V		–100	
I _{OZ}	High-impedance-state output current	V _O = –0.25 V to 6 V			±100	µA
I _{IH}	High-level input current	V _I = 2.7 V			20	µA
I _{IL}	Low-level input current	V _I = 0.4 V			–100	µA
I _{OS}	Short-circuit output current ^{(2) (3)}	V _O = V _{CC} or GND	–30		–150	mA
I _{CC}	Supply current (total package)	No load	Output enabled		80 110	mA
			Output disabled		50 80	

(1) All typical values are at V_{CC} = 5 V and T_A = 25°C.

(2) Refer to TIA-EIA-422-B for exact conditions.

(3) Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

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Switching Characteristics

$V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{d(OD)}$ Differential output delay time	$R_L = 100\ \Omega$, $C_L = 50\text{ pF}$, See Figure 3		20	25	ns
$t_{t(OD)}$ Differential output transition time	$R_L = 100\ \Omega$, $C_L = 50\text{ pF}$, See Figure 3		27	35	ns
t_{PLH} Propagation delay time, low- to high-level output	$R_L = 27\ \Omega$, See Figure 4		20	25	ns
t_{PHL} Propagation delay time, high- to low-level output	$R_L = 27\ \Omega$, See Figure 4		20	25	ns
t_{PZH} Output enable time to high level	$R_L = 110\ \Omega$, See Figure 5		80	120	ns
t_{PZL} Output enable time to low level	$R_L = 110\ \Omega$, See Figure 6		40	60	ns
t_{PHZ} Output disable time from high level	$R_L = 110\ \Omega$, See Figure 5		90	120	ns
t_{PLZ} Output disable time from low level	$R_L = 110\ \Omega$, See Figure 6		30	45	ns

RECEIVER SECTION

Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IT+} Positive-going input threshold voltage, differential input				0.2	V
V_{IT-} Negative-going input threshold voltage, differential input		-0.2 ⁽²⁾			V
V_{hys} Input hysteresis ($V_{IT+} - V_{IT-}$)			50		mV
V_{IK} Input clamp voltage, \overline{RE}	SN7534050 $I_I = -18\text{ mA}$			-1.5	V
V_{OH} High-level output voltage	$V_{ID} = 200\text{ mV}$, $I_{OH} = -400\ \mu\text{A}$, See Figure 2	2.7			V
V_{OL} Low-level output voltage	$V_{ID} = -200\text{ mV}$, See Figure 2			0.45 0.5	V
I_{OZ} High-impedance-state output current	SN7534050 $V_O = 0.4\text{ V to } 2.4\text{ V}$			± 20	μA
I_I Line input current	Other input at 0 V			1.5 -2.5	mA
I_{IH} High-level enable input current, \overline{RE}	SN7534050 $V_{IH} = 2.7\text{ V}$			20	μA
I_{IL} Low-level enable input current, \overline{RE}	SN7534050 $V_{IL} = 0.4\text{ V}$			-100	μA
r_i Input resistance		12			k Ω
I_{OS} Short circuit output current		-15		-85	mA
I_{CC} Supply current (total package)	No load, enabled		80	110	mA

(1) All typical values are at $V_{CC} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

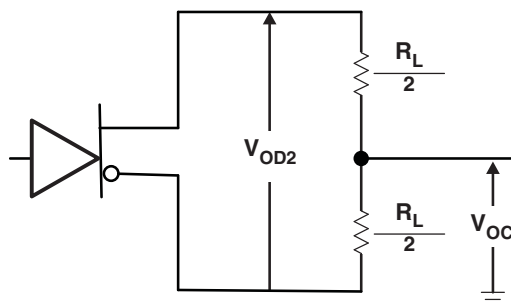
(2) The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels.

Switching Characteristics

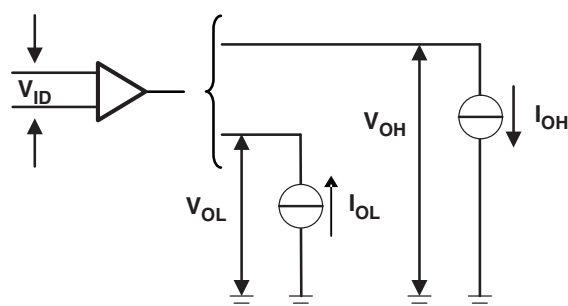
over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} Propagation delay time, low- to high-level output	$V_{ID} = 1.5\text{ V}$, $C_L = 15\text{ pF}$, See Figure 7		20	35	ns
t_{PHL} Propagation delay time, high- to low-level output	$V_{ID} = 1.5\text{ V}$, $C_L = 15\text{ pF}$, See Figure 7		22	35	ns
t_{PZH} Output enable time to high level	SN7534050 $C_L = 15\text{ pF}$, see Figure 8		17	25	ns
t_{PZL} Output enable time to low level	SN7534050 $C_L = 15\text{ pF}$, See Figure 8		20	27	ns
t_{PHZ} Output disable time from high level	SN7534050 $C_L = 15\text{ pF}$, See Figure 8		25	40	ns
t_{PLZ} Output disable time from low level	SN7534050 $C_L = 15\text{ pF}$, See Figure 8		30	40	ns

PARAMETER MEASUREMENT INFORMATION

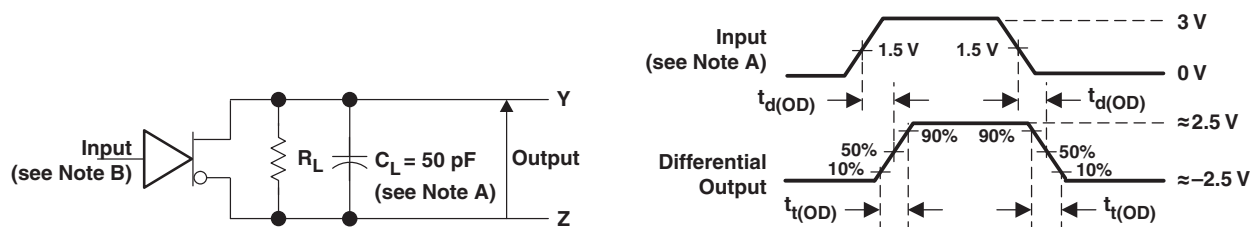


**Figure 1. Driver Test Circuit,
 V_{OD} and V_{OC}**



**Figure 2. Receiver Test Circuit,
 V_{OH} and V_{OL}**

- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_r = t_f \leq$ 6 ns.



TEST CIRCUIT

VOLTAGE WAVEFORMS

**Figure 3. Driver Test Circuit and Voltage Waveforms,
 $t_{d(OD)}$ and $t_{t(OD)}$**

- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_r = t_f \leq$ 6 ns.

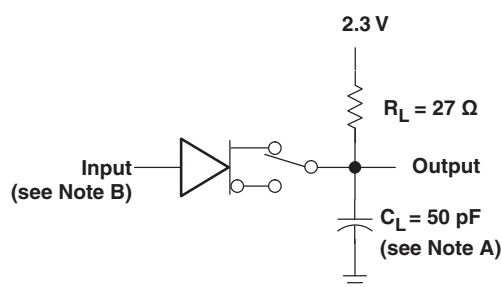
SN7534050, SN7534051



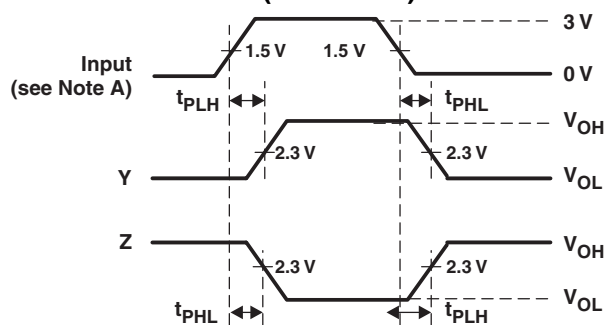
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PARAMETER MEASUREMENT INFORMATION (continued)



TEST CIRCUIT

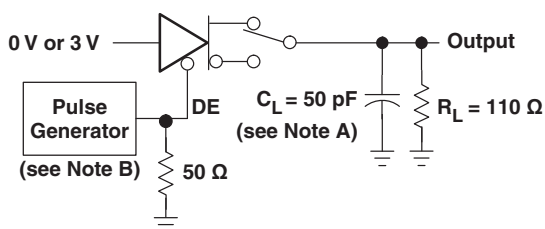


VOLTAGE WAVEFORMS

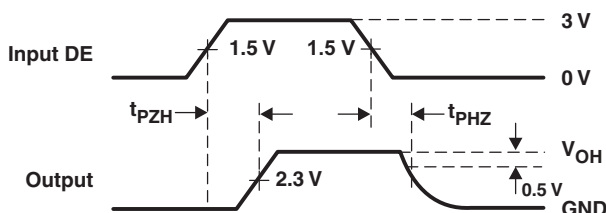
Figure 4. Driver Test Circuit and Voltage Waveforms, t_{PLH} and t_{PHL}

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_r = t_f \leq$ 6 ns.



TEST CIRCUIT

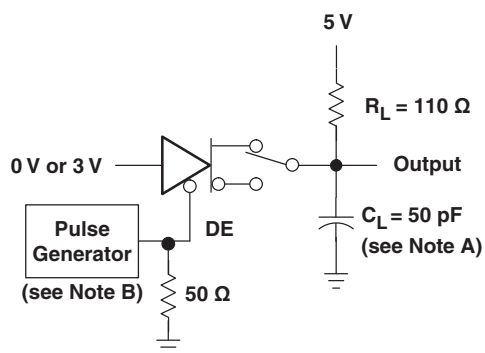


VOLTAGE WAVEFORMS

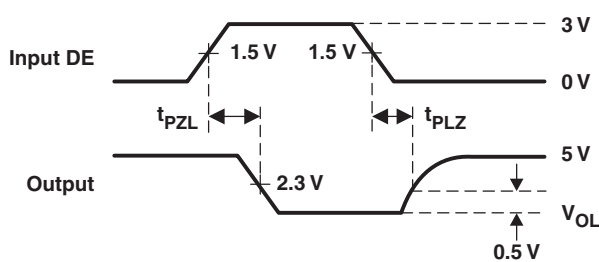
Figure 5. Driver Test Circuit and Voltage Waveforms, t_{PZH} and t_{PHZ}

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_r = t_f \leq$ 6 ns.



TEST CIRCUIT



VOLTAGE WAVEFORMS

Figure 6. Driver Test Circuit and Voltage Waveforms, t_{PZL} and t_{PLZ}

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_r = t_f \leq$ 6 ns.

PARAMETER MEASUREMENT INFORMATION (continued)

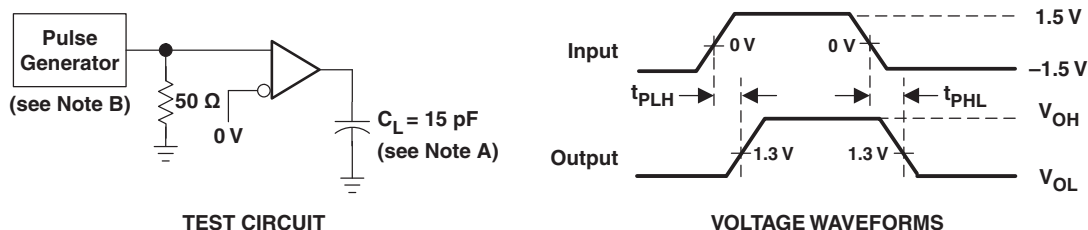


Figure 7. Receiver Test Circuit and Voltage Waveforms, t_{PLH} and t_{PHL}

- A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_r = t_f \leq$ 6 ns.

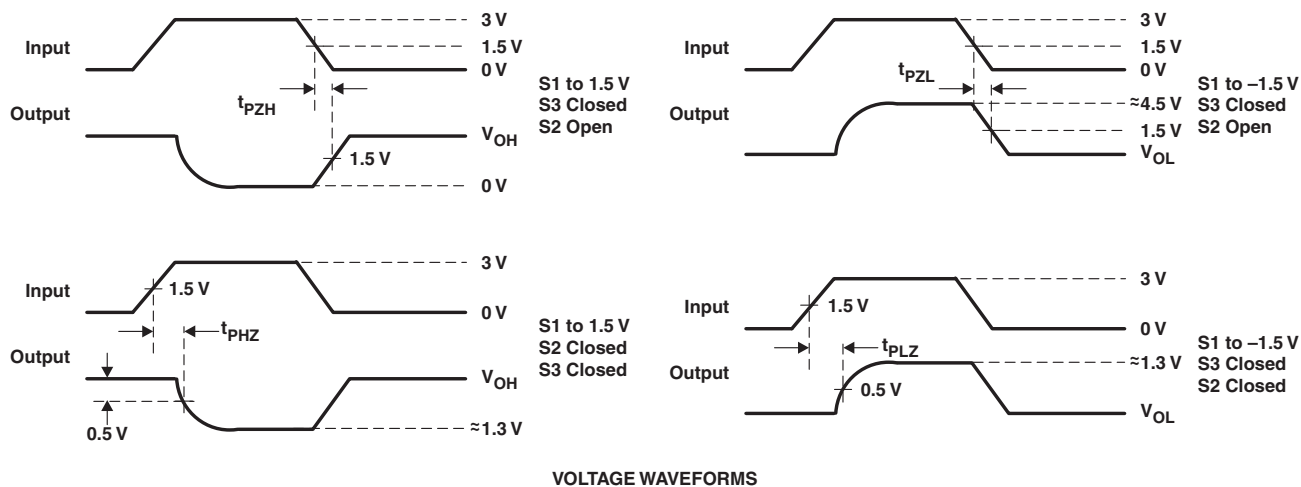
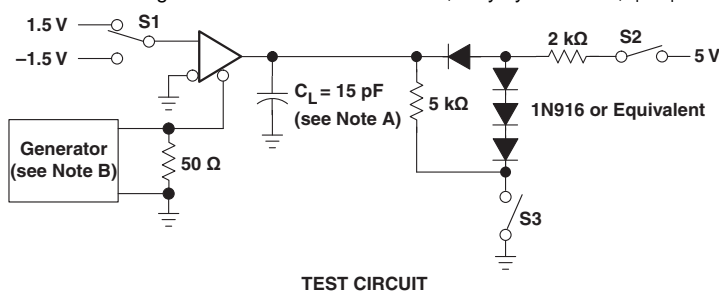


Figure 8. Receiver Test Circuit and Voltage Waveforms, t_{PZH} , t_{PZL} , t_{PHZ} , t_{PLZ} (SN7534050)

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REVISION HISTORY

Changes from Original (May 2007) to Revision A	Page
• Updated document format from QS to DocZone.	1
• Updated ORDERING INFORMATION table.	1

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN7534050N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		SN7534050N	Samples
SN7534050NS	ACTIVE	SO	NS	16	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		SN7534050	Samples
SN7534050NSG4	ACTIVE	SO	NS	16	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		SN7534050	Samples
SN7534050NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		SN7534050	Samples
SN7534051N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type		SN7534051N	Samples
SN7534051NS	ACTIVE	SO	NS	16	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		SN7534051	Samples
SN7534051NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		SN7534051	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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PACKAGE OPTION ADDENDUM

10-Jun-2014

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN7534051NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

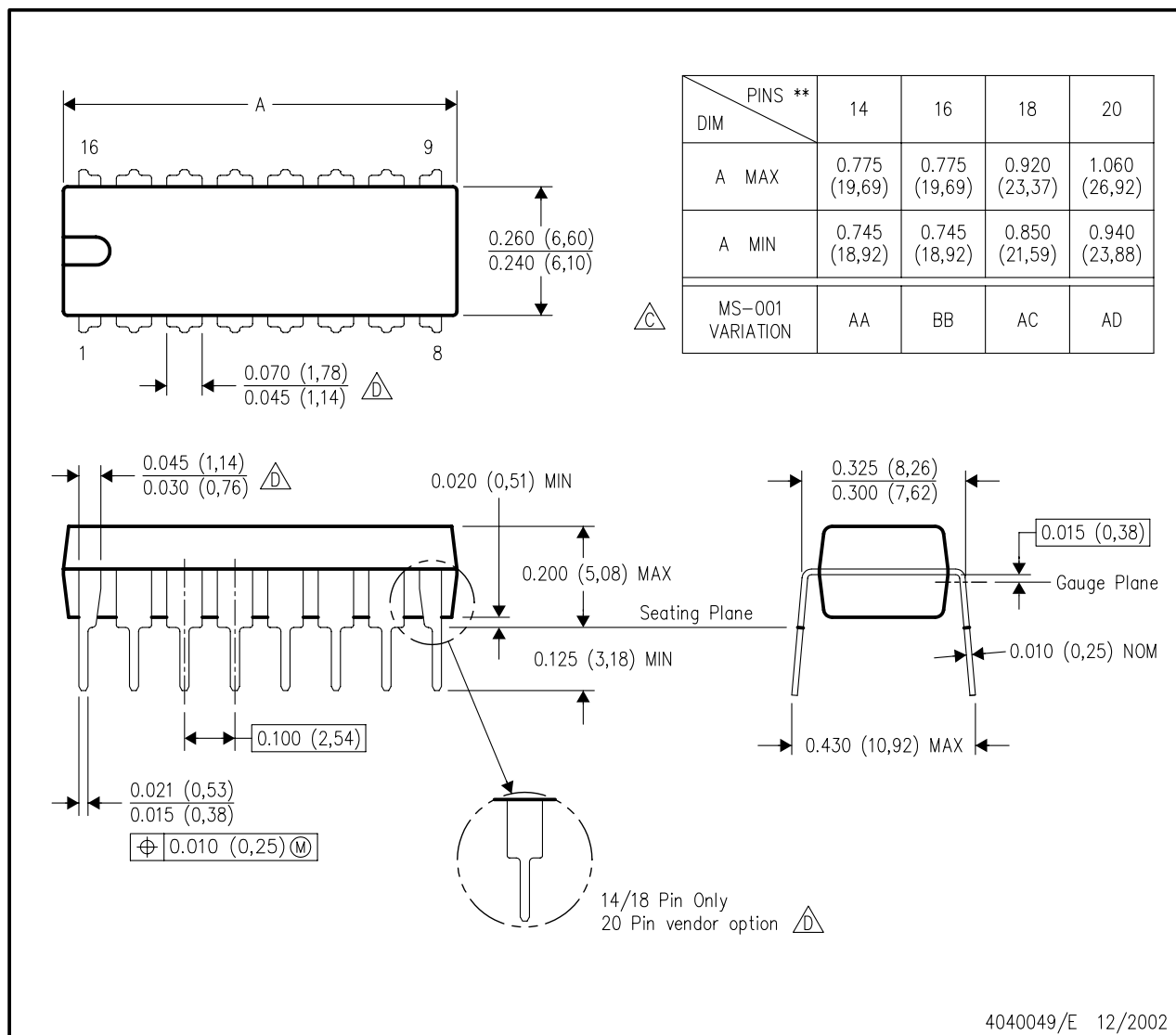
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN7534051NSR	SO	NS	16	2000	367.0	367.0	38.0

MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



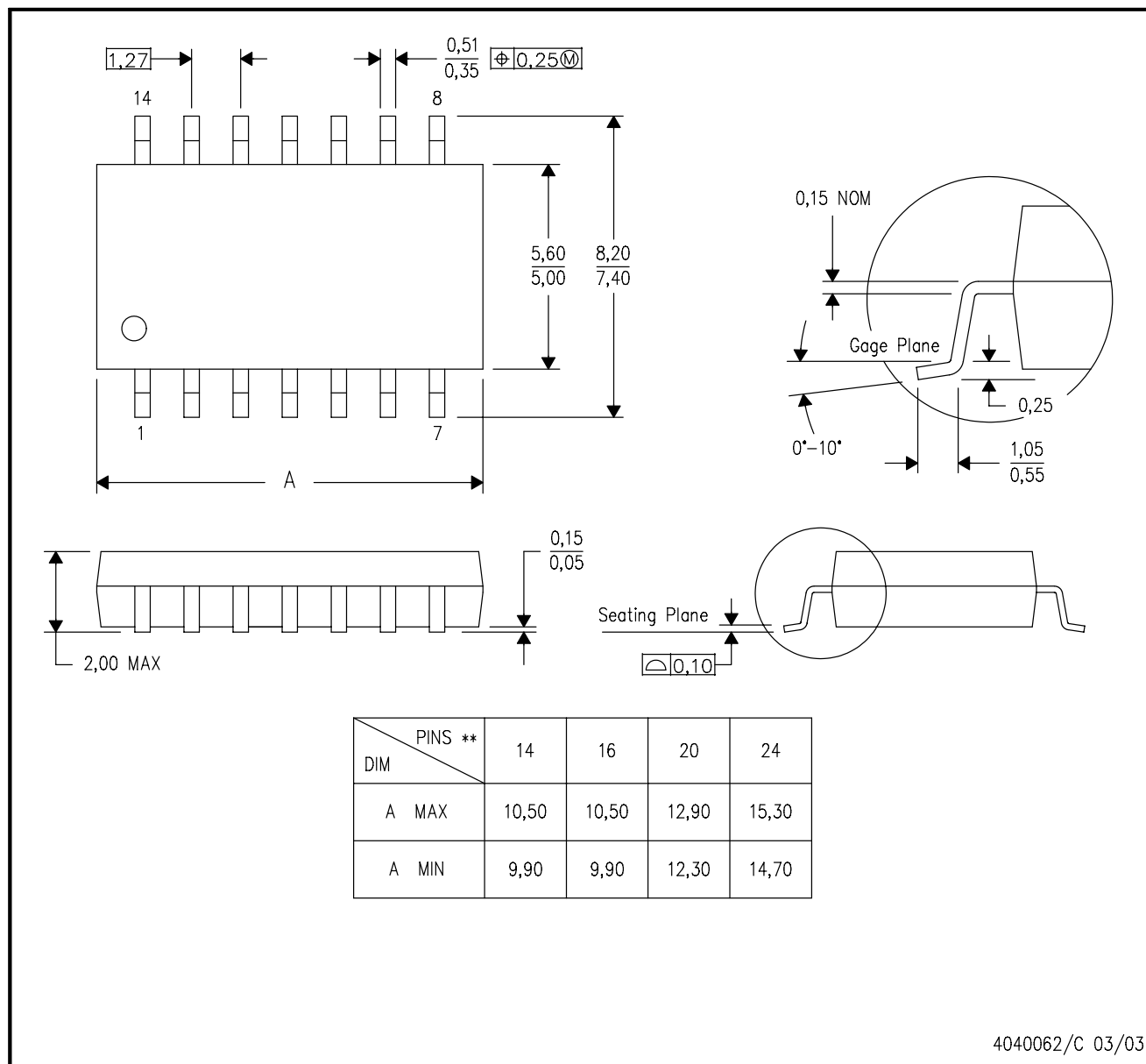
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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